

# LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC1798CS8-4.1#TRPBF

(Engineering Calculation)

SOIC

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TOTAL MASS (g):

0.07303085

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001762	1000000	24126.79		
Die Coat	Dow Corning	Silicone	67762-90-7	7.3E-05	1000000	999.5776		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0	0	0		
		Iron (Fe)	7439-89-6	0.014071	580000	192672		
		Phosphorus (P)	7723-14-0	0	0	0		
		Zinc (Zn)	7440-66-6	0	0	0		
		Nickel (Ni)	7440-02-0	0.010189	420000	139516.4		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
<b>Lead Frame Total:</b>				<b>0.02426</b>	<b>1000000</b>	<b>332188.4</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.001476852	1000000	20222.3		
		<b>External Plating Total:</b>				<b>0.001476852</b>	<b>1000000</b>	<b>20222.3</b>
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	0.000194	1000000	2656.411		
<b>Internal Plating Total:</b>				<b>0.000194</b>	<b>1000000</b>	<b>2656.411</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000631	750000	8640.184		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Resin (EP)		0.00021	250000	2875.497		
<b>Die Attach Total:</b>				<b>0.000841</b>	<b>1000000</b>	<b>11515.68</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006636	150000	90865.7		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.036276	820000	496721.6		
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0		
		Metal Hydroxid		0.001106	25000	15144.29		
		Carbon Black (C)	1333-86-4	0.000221	5000	3026.118		
		<b>Encapsulation Total:</b>				<b>0.044239</b>	<b>1000000</b>	<b>605757.6</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000185	1000000	2533.176		